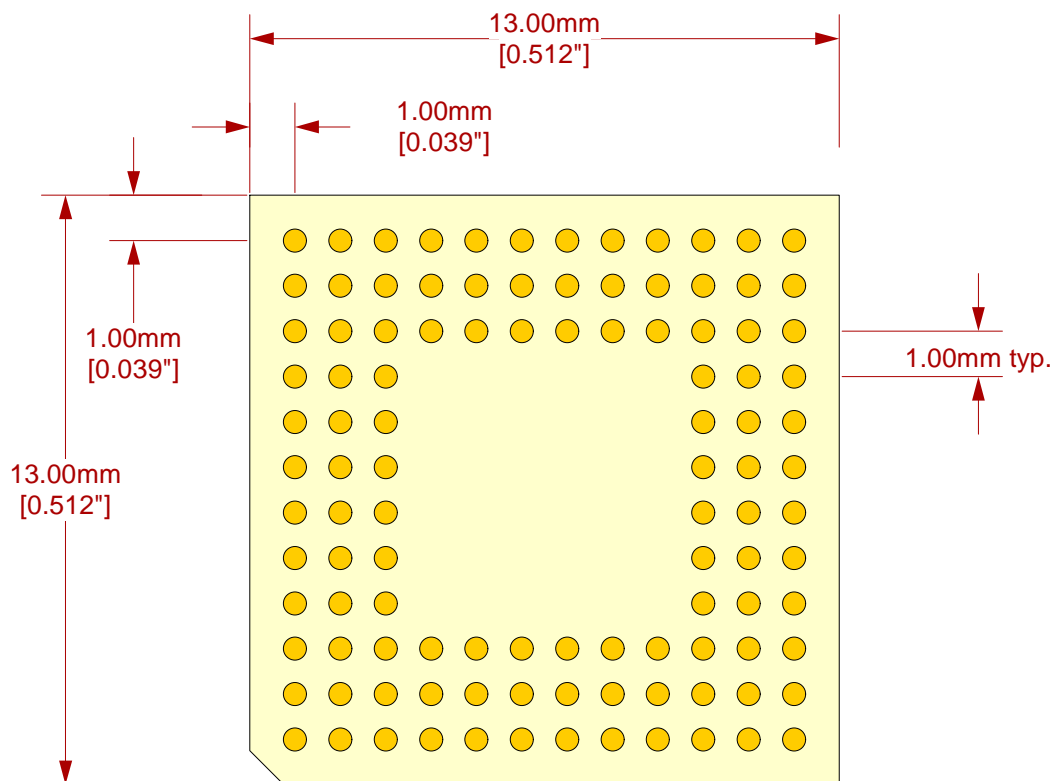
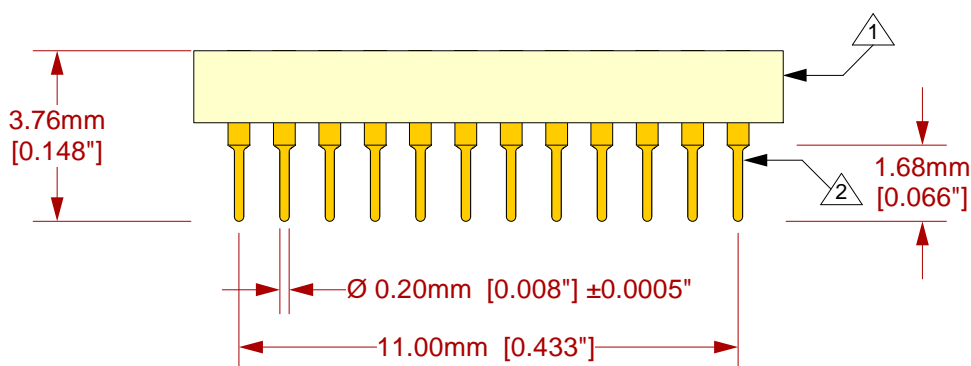


Top View



Side View




1 Substrate: 1.59mm $\pm 0.18\text{mm}$ [0.0625" $\pm 0.007\text{"}$] FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μm [10 μm] Au over 1.27 μm [50 μm] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

108 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 12x12 array)

Tolerances: diameters $\pm 0.03\text{mm}$ [$\pm 0.001\text{"}$], PCB perimeters $\pm 0.13\text{mm}$ [$\pm 0.005\text{"}$], PCB thicknesses $\pm 0.18\text{mm}$ [$\pm 0.007\text{"}$], pitches (from true position) $\pm 0.08\text{mm}$ [$\pm 0.003\text{"}$], all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005\text{"}$] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA108B-41 Drawing	Status: Released	Scale: 6:1	Rev: B
 © 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: B. Fedde	Date: 8/23/04	
	File: LS-BGA108B-41 Dwg	Modified: 4/18/05	